G2C+

T STRATEGY ALLIANCE

2467.TW
c sun志聖

5443.TW
GPM均豪

6640.TW
GMM均華

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements“. C Sun cautions readers that forward looking statements are based on C Sun’s reasonable knowledge and current expectations and are subject to various risks and uncertainties.

- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicality, customer’s financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun’s business and operations.

- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.

經營理念
皆大歡喜

G2C+

合力共創 同行致遠

善意的動機 引領事業走向成功

不論是在開創事業，或是在挑戰新任務時，我會先思考：

這是不是對世人有利？是不是利他的行為？

凡是能確信是基於利他、發自「善意動機」的事業，

最後無一例外，都能獲得好結果。

--- 摘自《心》稻盛和夫---

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5443.TW GPM均豪

6640.TW GMM均華

志聖工業

Stock No. 2467.TW

c sun志聖

G2C聯合法說

櫃買中心

G2C+
T STRATEGY ALLIANCE

聯盟總人數：1700+

R&D 人數：560+

R&D佔聯盟總人數比例達 32.5%

1966年

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Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

1978年

GPM均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

1978年

GMM均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

聯盟核心技術&綜效

c sun 壓合
貼膜
撕膜
熱製程

GPM 檢測
量測
研磨
拋光

GMM 黏晶
揀晶
切單挑揀

先進封裝

IC Substrate HBM Packaging 2.5/3DIC

G2C+

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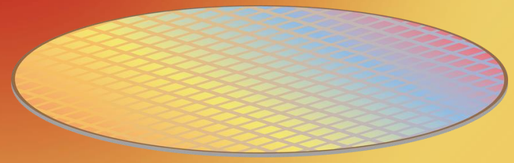


c sun GPM

晶圓製造

Reclaim Wafer

AI 發展四階段

感知 AI

感知圖像、
聲音、環境資訊

2012 年
AlexNet

NVIDIA

生成式AI

內容生成理解
(語言、圖像)

Chat GPT

Gemini

ANTHROPIC

Deepseek

推理 AI

理解規則、使用
工具、解決問題

AI Agent

Deepseek

實體 AI

具備因果推理、
物理直覺

NVIDIA
Cosmos AI

NVIDIA

2025/4/30國會山與矽谷論壇（Hill and Valley Forum）

臺灣西部黃金走廊：AI晶片

先進封裝製程的閃亮鑽石鏈

臺灣在**封裝測試**市場
的價值佔有率

58.6%

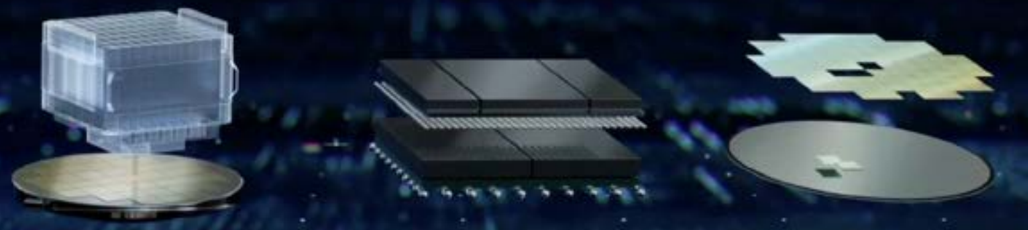
76.8%

臺灣在**晶圓製造**市場
的價值佔有率

c sun

晶圓大廠
向下整合
Foundry + Advanced Packaging + Testing
(InFo、CoWoS、SoIC)
先進封裝
Advanced Packaging
Flip Chip > Fan out > 2.5D/3D + Testing
(SiP、PoP、McM、FoCoS)
OSAT
向上發展

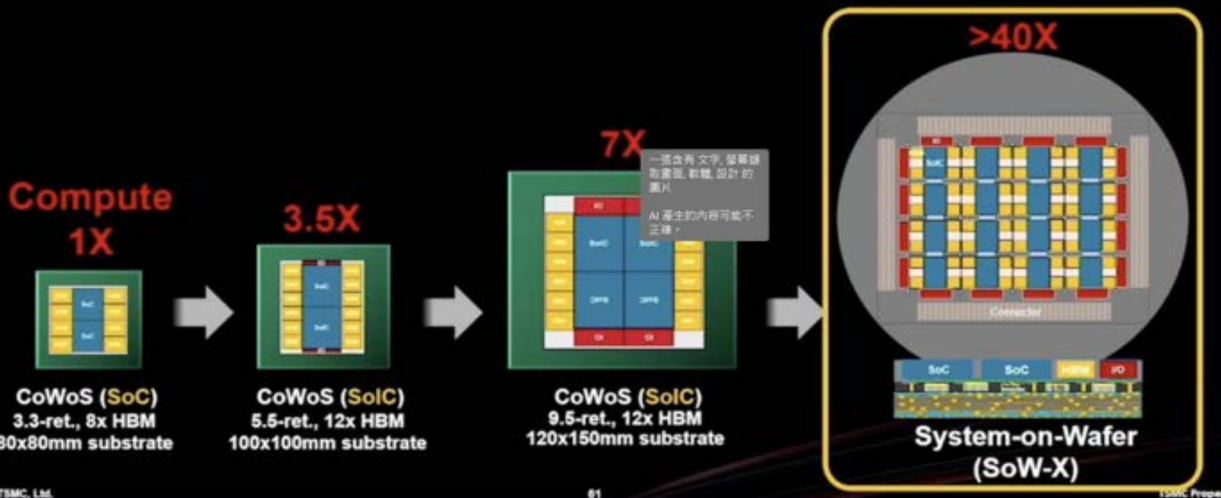
2022-2026 Expansion Capacity CAGR



AI Testing	CoWoS®	TSMC-SoIC®
80+%	80+%	100+%

TSMC-SoW™ (System-on-Wafer) Boosts AI Compute

- Wafer-scale integration maximizes computing power
- SoW-X technology for wafer-scale logic and HBM integration will be ready in 2027



CoWoS (SoC)
3.3-ret., 8x HBM
80x80mm substrate

CoWoS (SoIC)
5.5-ret., 12x HBM
100x100mm substrate

CoWoS (SoIC)
9.5-ret., 12x HBM
120x150mm substrate

System-on-Wafer (SoW-X)

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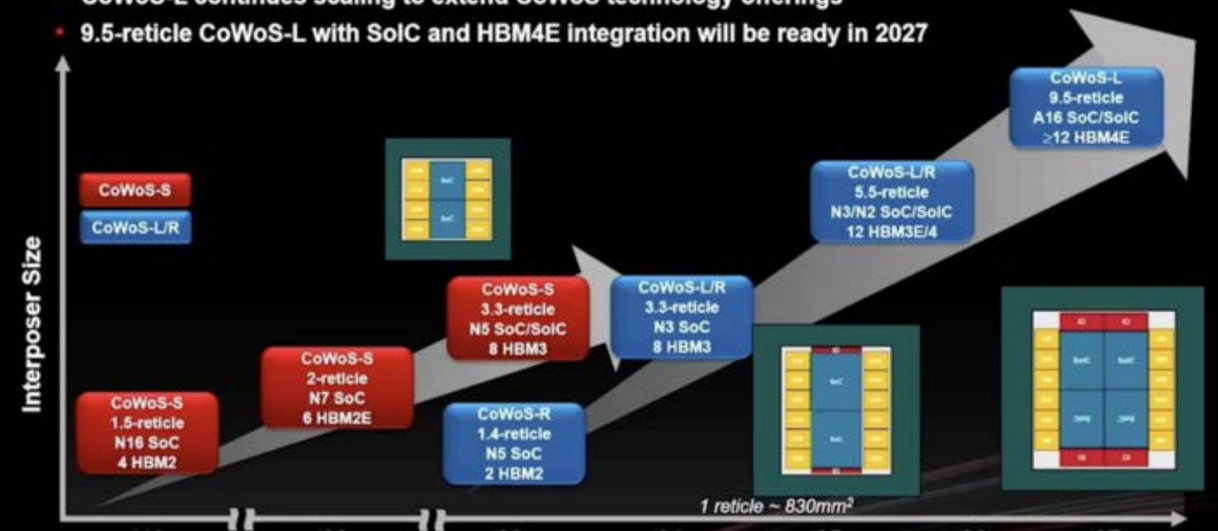
TSMC Property

CoWoS® Enables AI Compute Scaling

- CoWoS-S has been in production for over 10 years with interposer size up to 3.3-reticle
- CoWoS-L continues scaling to extend CoWoS technology offerings
- 9.5-reticle CoWoS-L with SoIC and HBM4E integration will be ready in 2027



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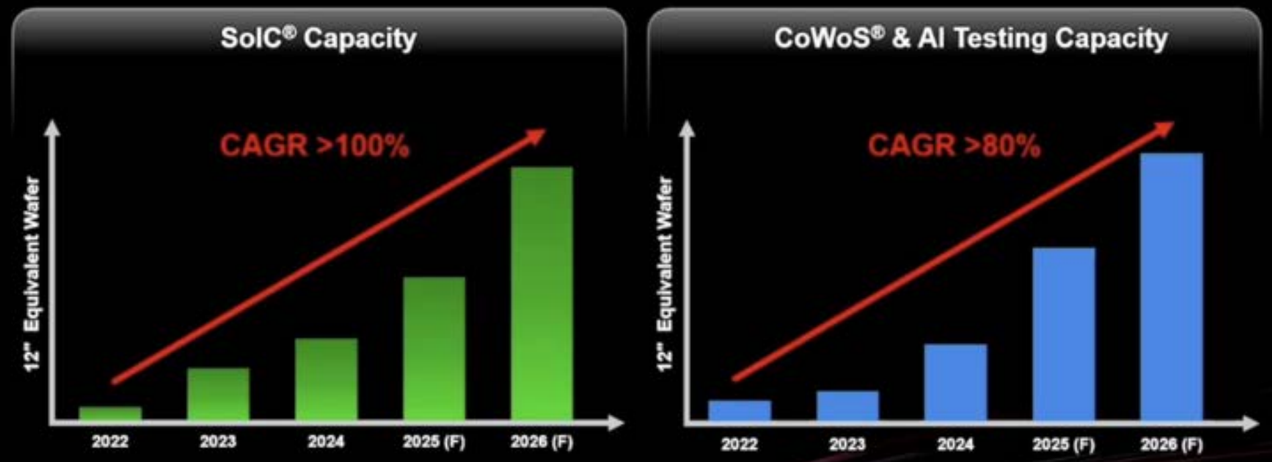
TSMC Property

TSMC 3DFabric® Capacity Growth

- Accelerating 3DFabric™ capacity expansion to support explosive HPC/AI demand



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TSMC Property

c sun志聖 公司簡介

2023 、2024
TSMC Award

員工與家族
持股>40%

1966.9.28 創立
資本額:15.6億
董事長:梁茂生
總經理:梁又文

全球貿易變局:
關稅壓力 &
匯率波動

FOB 交易條件為主

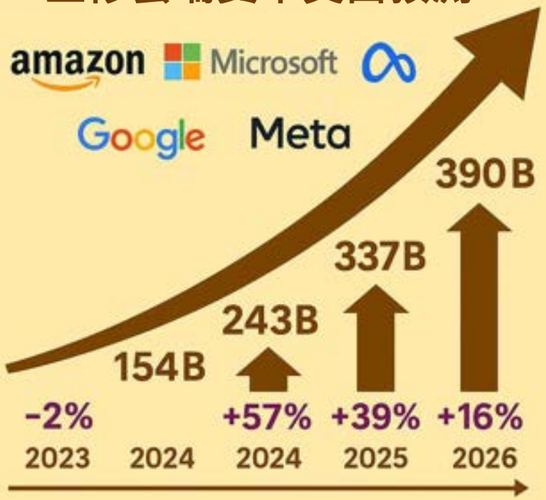
過去三年

關鍵客戶
交易幣別

c sun志聖

2025營業目標
持續、緊跟領先
客戶技術發展

美國四大雲端業者持續
上修雲端資本支出預測



需求預估不變

真空壓力烤箱

業務增長

與關鍵客戶
持續開發中

財務回顧

綜合損益表項目 *(除另予註明者外，金額為新台幣百萬元)*	1Q25	4Q24	1Q24	QoQ 季變化	YoY 同比
營業收入淨額	1,309	1,335	1,080	-2.0%	21.2%
營業毛利率%	43.0%	41.9%	43.2%	+1.1ppts	-0.2ppts
營業費用	(383)	(336)	(312)	14%	23%
營業費用率%	29.2%	25.1%	28.9%	+4.1ppts	+0.3ppts
營業利益率%	13.8%	16.7%	14.3%	-2.9ppts	-0.5ppts
營業外收入與支出	59	77	86	-23%	-31%
歸屬予母公司業主之本期淨利	150	195	172	-23%	-13%
純益率%	11.5%	14.6%	15.9%	-3.1ppts	-4.4ppts
每股盈餘(新台幣元)	1	1.3	1.15	-23%	-13%

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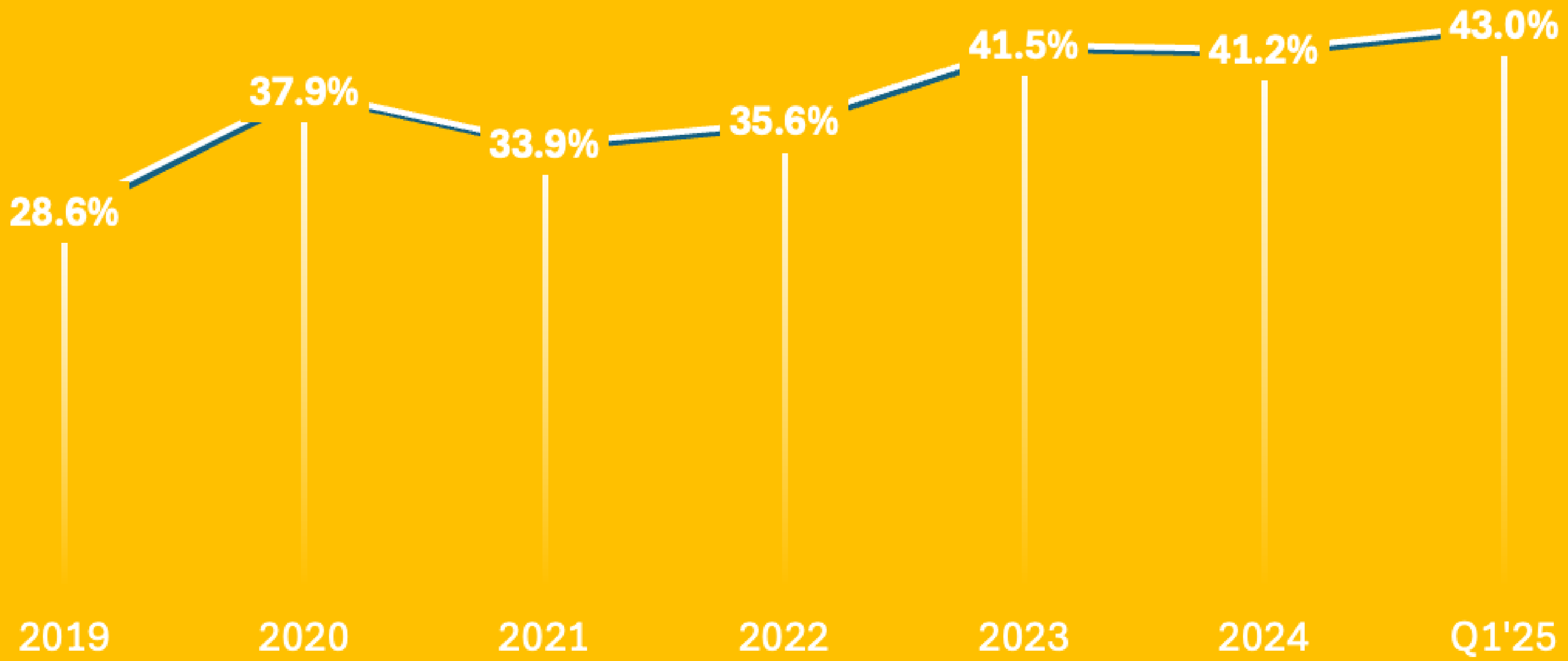
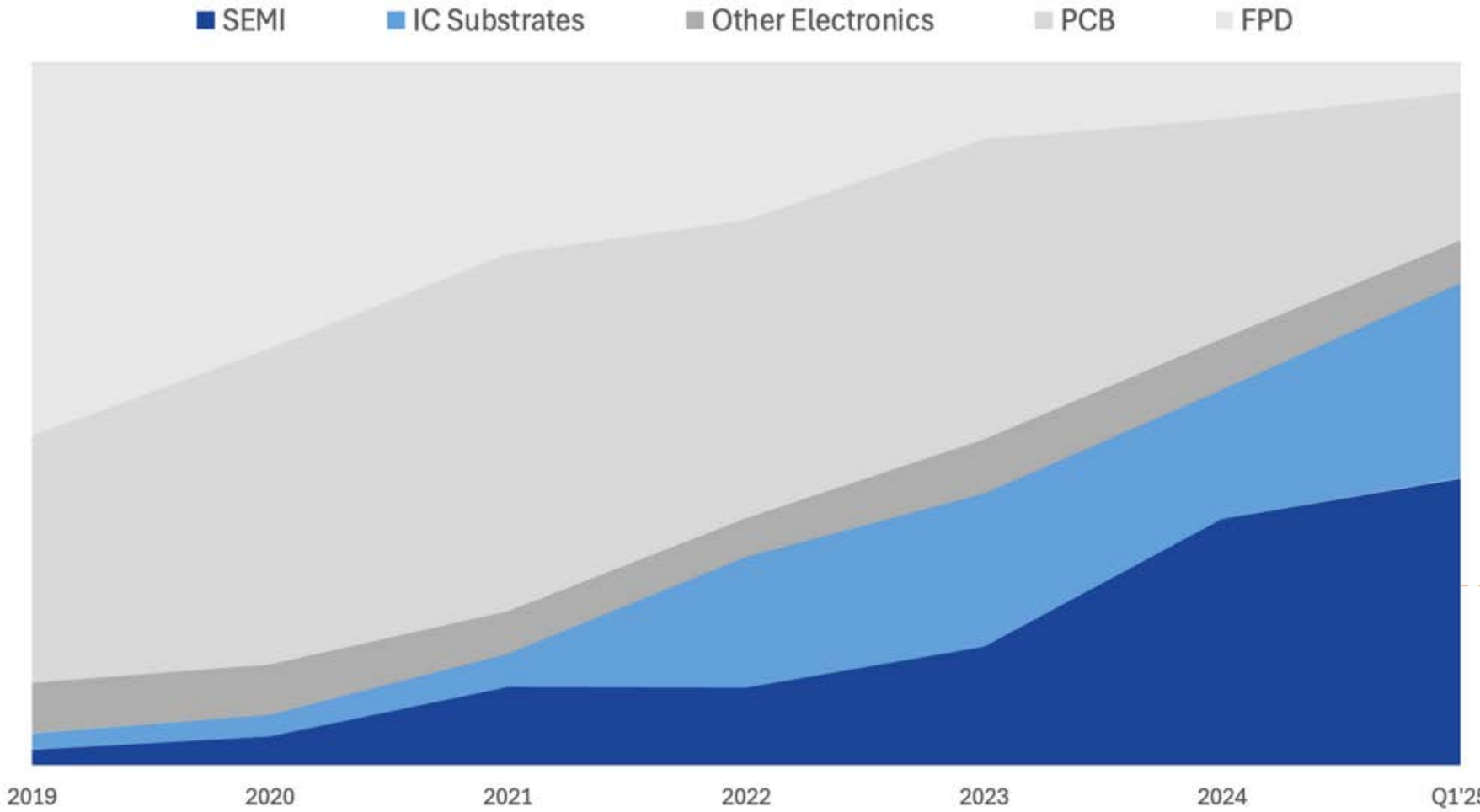
毛利率變化



營收組成變化



SEMI~40%

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封測廠OSATs的收入佔比增長

世界前10大封測廠OSATs均為G2C+的客戶

4% 10%

ASE Amkor Technology JCET 通富微電 PTI HUA TIAN

KYEC ChipMOS CHIPBOND 頎邦科技

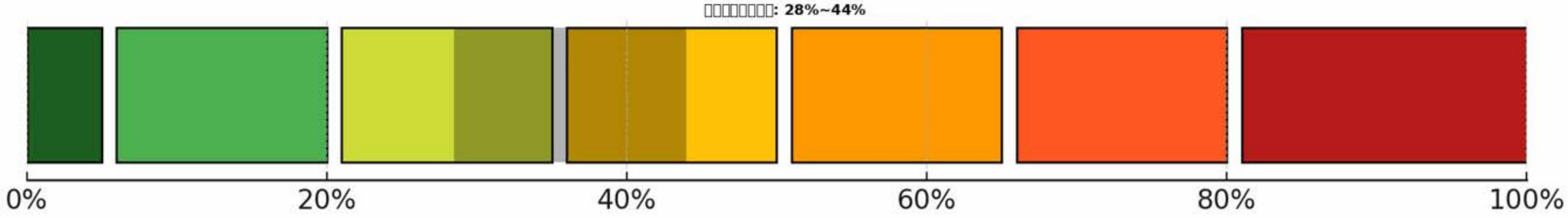
csun志聖

Focusing
AI 聚焦
HBM
oS
LPO
Assembly
IC Substrate
CoW
SoC/SoIC
CPO
Test
Mother Board
2024
>50%

12th公司治理評鑑

維護股東權益及平

強化董事會結構



提升資訊透明度

推動永續發展

G2C+

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Exhibition Preview

SEMICON® SOUTHEAST ASIA 30 YEARS Special Edition

MAY 20-22, 2025 10:00~17:00 SGT

SANDS EXPO & CONVENTION CENTRE SINGAPORE

BASEMENT 2

B1524

We sincerely invite you to visit our exhibition booth for inquiries. Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

ECTC 75 2025

The 2025 IEEE 75th Electronic Components and Technology Conference

May 27 – 30, 2025

Gaylord Texan Resort & Convention Center Dallas, Texas, USA

Booth No. 111

We sincerely invite you to visit our exhibition booth for inquiries. Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

Invitation

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A G2C+ Alliance Company

Thank you for your attention